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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Inventors: Masanori MINAMIO, et al.

Application No.: New PCT Application

Filed: August 31, 1999

For: RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND A  
METHOD OF MANUFACTURING THE SAME

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents  
Washington, DC 20231

Sir:

IN THE CLAIMS

Please amend claim 7 as follows:

Claim 7, line 2, after "1," delete "2, 3, 4, 5, or 6".

Please add the following new claims:

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--11. A resin molded type semiconductor device according to claim 2, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.

--12. A resin molded type semiconductor device according to claim 3, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.

--13. A resin molded type semiconductor device according to claim 4, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.

--14. A resin molded type semiconductor device according to claim 5, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.

--15. A resin molded type semiconductor device according to claim 6, wherein exposed faces of said outer lead portion are arranged in a same level as an outer face of said sealing resin.--

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